EN E-004237/2021 Answer given by Mr Breton on behalf of the European Commission (17.3.2022)

The Digital Compass Communication¹ from 9 March 2021 and more recently the proposed 2030 Policy Programme 'Path to the Digital Decade'² indicate that the production of cuttingedge and sustainable semiconductors in the Union should be at least 20% of world production in value by 2030.

The Commission published the proposal for the EU Chips Act on 8 February 2022³. The EU Chips Act consists of measures to ensure the EU's security of supply, resilience and technological leadership in semiconductor technologies and applications.

The overall level of policy-driven investment in support of the EU Chips Act is estimated to be in excess of EUR 43 billion up to 2030. EUR 11 billion of public funding is foreseen for the Chips for Europe Initiative to finance technology leadership in research, design and manufacturing capabilities up to 2030, and includes EUR 5.3 billion from Member States. In addition, Member States are expected to invest around EUR 30 billion including in Important Projects of Common European Interest and large manufacturing facilities. This includes State aid for 'first-of-a-kind' facilities, which are not substantively already present or committed to be built within the EU. First-of-a-kind does not refer exclusively to the size of the node but also for instance to the technology node, product material or other product innovation or energy and environmental performance.

The Chips for Europe Initiative includes a component on design, which will be managed by the Chips Joint Undertaking. The amount of funding going into design will be decided by the Governing Board of the Joint Undertaking, including participating states, the Commission, and industry.

¹ COM/2021/118: https://eur-lex.europa.eu/legal-content/en/TXT/?uri=CELEX%3A52021DC0118

² https://digital-strategy.ec.europa.eu/en/library/proposal-decision-establishing-2030-policy-programme-path-digital-decade

³ https://ec.europa.eu/commission/presscorner/detail/en/STATEMENT 22 891